

PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E.

PATENT DATE

SCANNED

Q.A.

APPLICATION NO.
09/596637

CONT/PRIOR

CLASS

SUBCLASS

ART UNIT

EXAMINER

APPLICANTS

TITLE

Method for fabricating microstructures with deep anisotropic etching of thick silicon wafers

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL				CROSS REFERENCE(S)					
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)				
438				438					
INTERNATIONAL CLASSIFICATION									
H01L 21/302									

☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg. 18	Figs. Drwg. 75	Print Fig.	Total Claims 115
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) _____ (Date)		NOTICE OF ALLOWANCE MAILED	
	<input checked="" type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____ _____ _____	<i>George Goudreau 7-03'</i> GEORGE GOUDREAU PRIMARY EXAMINER _____ (Primary Examiner) _____ (Date)	ISSUE FEE	
Amount Due			Date Paid	
<input checked="" type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)		ISSUE BATCH NUMBER	
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